



This certificate is granted and awarded by the authority of the Nadcap Management Council to:

***Benchmark Electronics Manufacturing Solutions
(Moorpark), Inc.***

*200 Science Drive
Moorpark, CA 93021
United States*

This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in www.eAuditNet.com on the Qualified Manufacturers List (QML), to the revision in effect at the time of the audit for:

Electronics

Certificate Number: 12959179527
Expiration Date: 31 October 2018

Joseph G. Pinto
Executive Vice President and Chief Operating Officer



SCOPE OF ACCREDITATION

Electronics

Benchmark Electronics Manufacturing Solutions (Moorpark), Inc.

200 Science Drive
Moorpark, CA 93021

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7120 Rev E - Nadcap Audit Criteria for Circuit Card Assemblies (to be used on audits on/after 9 April 2017)

- 04– General
- 05– Outsourced Processes
- 06– Process Control
- 07– Visual Acuity
- 08– Customer Data
- 09– Electrostatic Discharge (ESD)
- 10– Material Management
- 11– Moisture Sensitive Components and Materials
- 12– Kitting
- 13.1– In-Process Verification / Inspection: General
- 13.2– In-Process Verification / Inspection: Visual
- 13.3– In-Process Verification / Inspection: AOI
- 13.4– In-Process Verification / Inspection: X-Ray
- 14.1– Secondary Assembly: Mechanical Part Installation
- 14.2– Secondary Assembly: Wire Cutting & Stripping
- 14.3– Secondary Assembly: Jumper Wire Installation
- 14.4– Secondary Assembly: Stranded Wire Tinning
- 14.5– Secondary Assembly: Compliant Pin (Press Fit) Connector Installation
- 14.6– Secondary Assembly: Bonding
- 15– Cleanliness
- 16– Final Inspection
- 17– Rework

AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

- 03– General
- 04– Electronic Component Preparation for Preassembly Process
- 05.1– Part Placement: General
- 05.2– Part Placement: Manual
- 05.3– Part Placement: Clinched Component Leads
- 06– Gold Removal
- 07– Build Through / Build Short
- 08– Hand Soldering

AC7120/3 - Plated Through Hole Technology (to be used on audits on/after 9 April 2017)

- 04– Wave Soldering
- 05– Selective Soldering

AC7120/4 - Surface Mount Technology (to be used on audits on/after 9 April 2017)

- 03– Preparation
- 04– Stencil Printing
- 05– Automated Part Placement
- 06– Reflow Soldering

AC7120/5 - Mixed Metallurgy for BGAs (to be used on audits on/after 9 April 2017)

- 03– Lead-Free Control Plan (LFCP)
- 04– Qualification for Assemblies Containing BGAS

AC7120/6 - Lead Free Soldering (to be used on audits on/after 9 April 2017)

- 03– Lead-Free Control Plan (LFCP)
- 04– Process Control
- 05– Training

AC7120/7 - Conformal Coating of Printed Board Assemblies (to be used on audits on/after 9 April 2017)

- 04– Material
- 05– Material and Equipment Compatibility
- 06– Preparation / Cleaning
- 07– Application / Drying / Curing
- 08– Thickness
- 09– Inspection
- 10– Rework
- 11– Training

AC7120/9 - Programming (to be used on audits on/after 9 April 2017)

04– General

05– Component Programming (Prior to Assembly)

06– Circuit Card Assembly Programming

AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)

04– General